



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|------------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 0.78mm +/-0.10mm |
| S | 0.75mm MIN |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

| | |
|--------------------|------------------------|
| Packaging | T&R, 330mm, Paper Tape |
| Packaging Quantity | 15000 |

General Information

| | |
|------------------|--|
| Series | SMD Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 11 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|------------------------|
| Capacitance | 33 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Capacitance Tolerance | 5% |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |